



18 Output, 3.3V SDRAM Buffer for Desktop PCs with 3 DIMMs

Features

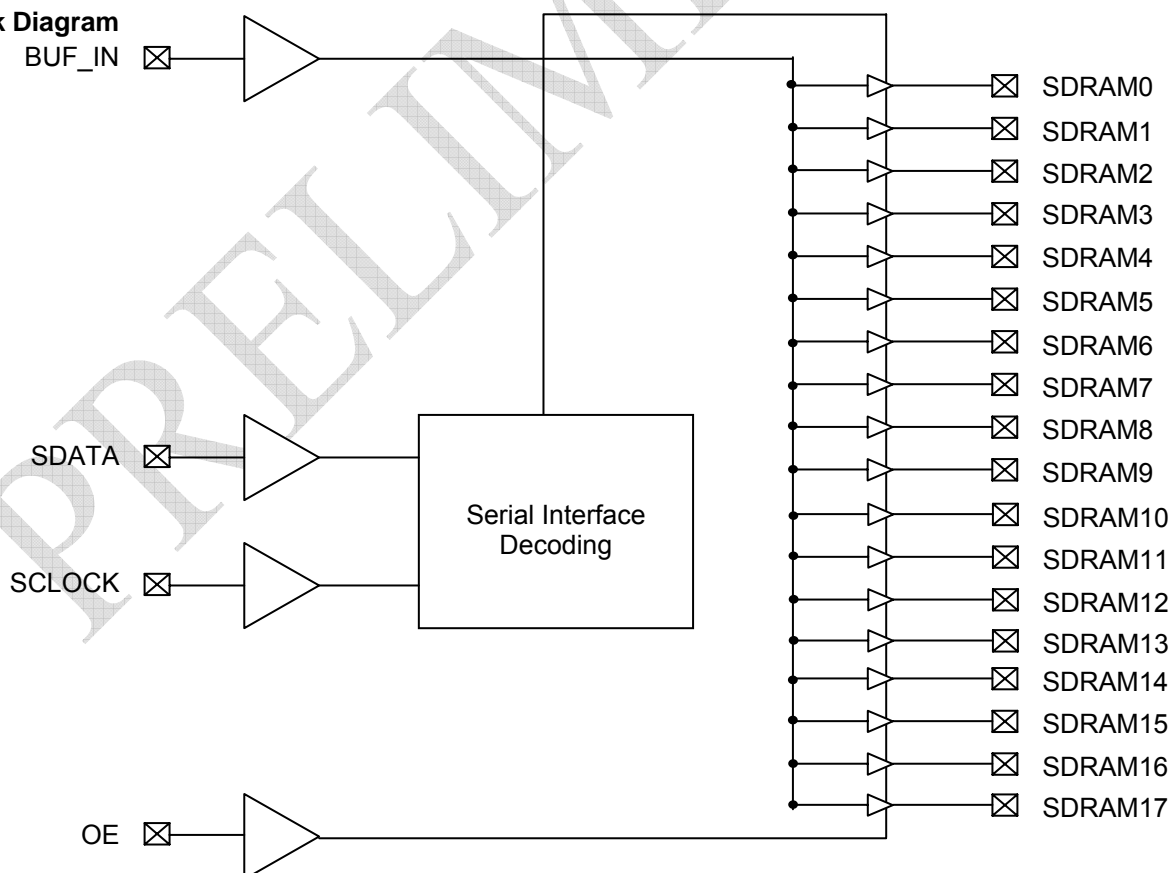
- One input to 18 output Buffer/Driver
- Supports up to four SDRAM DIMMs
- Two additional outputs for feedback
- Serial interface for individual output control
- Low skew outputs (< 250 pS)
- Up to 133 MHz operation
- Dedicated OE pin for testing
- Space-saving 48 Pin SSOP package
- 3.3V operation

Functional Description

The ASM2I2318ANZ is a 3.3V buffer designed to distribute high-speed clocks in PC applications. The part has 18 outputs, 16 of which can be used to drive up to four SDRAM DIMMs, and the remaining can be used for external feedback to a PLL. The device operates at 3.3V and outputs can run up to 133MHz, thus making it compatible with Pentium II® processors. The ASM2I2318ANZ can be used in conjunction with the clock synthesizer for a complete Pentium II motherboard solution. The ASM2I2318ANZ also includes a serial interface which can enable or disable each output clock. On power-up, all output clocks are enabled (internal pull up). A separate Output Enable pin facilitates testing on ATE.

*Pentium is a registered trademark of Intel Corporation.

Block Diagram

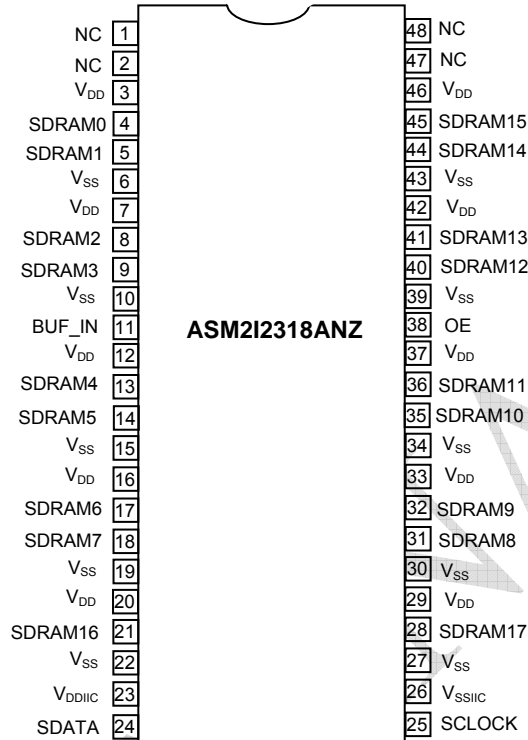




rev 0.3

Pin Configuration

48-Pin SSOP Package -- Top View



Pin Description

Pins	Name	Type	Description
3, 7, 12, 16, 20, 29, 33, 37, 42, 46	V _{DD}	P	3.3V Digital voltage supply
6, 10, 15, 19, 22, 27, 30, 34, 39, 43	V _{SS}	P	Ground
23	V _{DDIIC}	P	Serial interface voltage supply
26	V _{SSIIC}	P	Ground for serial interface
11	BUF_IN	I	Input clock. 5V tolerant
38	OE	I	Output Enable (active HIGH), Three-state outputs when low ¹
24	SDATA	I/O	Serial data input ¹ . 5V tolerant
25	SCLK	I	Serial clock input ¹ . 5V tolerant
4, 5, 8, 9	SDRAM [0–3]	O	SDRAM byte 0 clock outputs
13, 14, 17, 18	SDRAM [4–7]	O	SDRAM byte 1 clock outputs
31, 32, 35, 36	SDRAM [8–11]	O	SDRAM byte 2 clock outputs
40, 41, 44, 45	SDRAM [12–15]	O	SDRAM byte 3 clock outputs
21, 28	SDRAM [16–17]	O	SDRAM clock outputs usable for feedback
NC	1, 2, 47, 48	-	Reserved for future modifications, do not connect in system

Note: 1. Internal pull-up resistor to V_{DD} (value > 100 KOhms)



rev 0.3

Device Functionality

OE	SDRAM [0-17]
0	Hi-Z
1	1 x BUF_IN

Serial Configuration Map

- The Serial bits will be read by the clock driver in the following order:

Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0

- Reserved bits should be programmed to "0" or "1".
- Serial interface address for the ASM2I2318ANZ is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	---

**Byte 0:SDRAM Active/Inactive Register
(1 = Enable, 0 = Disable), Default = Enable**

Bit	Pin #	Description
Bit 7	18	SDRAM7 (Active/Inactive)
Bit 6	17	SDRAM6 (Active/Inactive)
Bit 5	14	SDRAM5 (Active/Inactive)
Bit 4	13	SDRAM4 (Active/Inactive)
Bit 3	9	SDRAM3 (Active/Inactive)
Bit 2	8	SDRAM2 (Active/Inactive)
Bit 1	5	SDRAM1 (Active/Inactive)
Bit 0	4	SDRAM0 (Active/Inactive)

Note 1 : When the value of bit in these bytes is high, the output is enabled. When the value of the bit is low, the output is forced to low state. The default value of all the bits is high after chip is powered up.

IIC Byte Flow

Byte	Description
1	IIC Address
2	Command (dummy value, ignored)
3	Byte Count (dummy value, ignored)
4	IIC Data Byte 0
5	IIC Data Byte 1
6	IIC Data Byte 2

**Byte 1: SDRAM Active/Inactive Register
(1 = Enable, 0 = Disable), Default = Enable**

Bit	Pin #	Description
Bit 7	45	SDRAM15 (Active/Inactive)
Bit 6	44	SDRAM14 (Active/Inactive)
Bit 5	41	SDRAM13 (Active/Inactive)
Bit 4	40	SDRAM12 (Active/Inactive)
Bit 3	36	SDRAM11 (Active/Inactive)
Bit 2	35	SDRAM10 (Active/Inactive)
Bit 1	32	SDRAM9 (Active/Inactive)
Bit 0	31	SDRAM8 (Active/Inactive)

**Byte 2: SDRAM Active/Inactive Register
(1 = Enable, 0 = Disable), Default = Enable**

Bit	Pin #	Description
Bit 7	28	SDRAM17 (Active/Inactive)
Bit 6	21	SDRAM16 (Active/Inactive)
Bit 5	--	Reserved
Bit 4	--	Reserved
Bit 3	--	Reserved
Bit 2	--	Reserved
Bit 1	--	Reserved
Bit 0	--	Reserved



rev 0.3

Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DD}	Supply Voltage to Ground Potential	-0.5 to +7.0	V
V_{IN}	DC Input Voltage (Except BUF_IN)	-0.5 to $V_{DD} + 0.5$	V
$V_{BUF_{IN}}$	DC Input Voltage (BUF_IN)	-0.5 to +7.0	V
T_{STG}	Storage Temperature	-65 to +150	°C
T_J	Junction Temperature	150	°C
T_{DV}	Static Discharge Voltage (As per JEDEC STD 22- A114-B)	2	KV

Note: These are stress ratings only and are not implied for functional use. Exposure to absolute maximum ratings for prolonged periods of time may affect device reliability.

Operating Conditions¹

Parameter	Description	Min	Max	Unit
$V_{DD} V_{DDIIC}$	Supply Voltage	3.135	3.465	V
T_A	Operating Temperature (Ambient Temperature)	0	70	°C
C_L	Load Capacitance	20	30	pF
C_{IN}	Input Capacitance		7	pF
t_{PU}	Power-up time for all V_{DD} 's to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	mS

Note: 1. Electrical parameters are guaranteed under the operating conditions specified.



rev 0.3

Electrical Characteristics

(Test condition: All parameters values are valid within the Operating range, unless otherwise stated)

Parameter	Description	Test Conditions	Min	Typ	Max	Unit
V_{IL}	Input LOW Voltage	For all pins except serial interface pins			0.8	V
V_{ILiic}	Input LOW Voltage	For serial pins only			0.7	V
V_{IH}	Input HIGH Voltage		2.0			V
V_{OL}	Output LOW Voltage ¹	$I_{OL} = 25\text{ mA}$			0.4	V
V_{OH}	Output HIGH Voltage ¹	$I_{OH} = -36\text{ mA}$	2.4			V
I_{CC}	Quiescent Supply Current	$V_{DD} = 3.465\text{V}$, $V_i = V_{DD}$ or GND, $I_o = 0$		50	100	μA
I_{OZ}	High Impedance Output Current	$V_{DD} = 3.465\text{V}$, $V_i = V_{DD}$ or GND			± 10	μA
I_{OFF}	Off-State Current (for SCL, SDATA)	$V_{DD} = 0\text{V}$, $V_i = 0\text{V}$ or 5.5V			50	μA
ΔI_{CC}	Change in Supply Current	$V_{DD} = 3.135\text{V}$ to 3.465V One Input at $V_{DD}-0.6$, All other Inputs at V_{DD} or GND			500	μA
I_i	Input Leakage	$V_{DD} = 3.465\text{V}$ or GND (Applicable to all Input Pins)	-5		+5	μA
I_{DD}	Supply Current ¹	Unloaded outputs, 133 MHz			150	mA
I_{DD}	Supply Current ¹	Loaded outputs, 30pF, 133 MHz			400	mA
I_{DD}	Supply Current ¹	Unloaded outputs, 100 MHz			110	mA
I_{DD}	Supply Current ¹	Loaded outputs, 30pF, 100 MHz			300	mA
I_{DD}	Supply Current ¹	Unloaded outputs, 66.67 MHz			80	mA
I_{DD}	Supply Current ¹	Loaded outputs, 30pF, 66.67 MHz			200	mA
I_{DDS}	Supply Current	BUF_IN= V_{DD} or V_{SS} , all other inputs at V_{DD}			500	μA

Note: 1. Parameter is guaranteed by design and characterization. Not 100% tested in production.



rev 0.3

Switching Characteristics¹

Parameter	Name	Test Conditions	Min	Typ	Max	Unit
F_{in}	Maximum Operating Frequency		-	-	133	MHz
t_D	Duty cycle ^{2,3} = $t_2 \div t_1$	Measured at 1.5V	45.0	50.0	55.0	%
t_3	Rising Edge Rate ³	Measured between 0.4V and 2.4V	1	2	4	V/nS
t_4	Falling Edge Rate ³	Measured between 2.4V and 0.4V	1	2	4	V/nS
t_5	Output to Output Skew ³	All outputs equally loaded		150	225	pS
t_6	SDRAM Buffer LH Prop. Delay ³	Input edge greater than 1 V/nS	1	2.7	3.5	nS
t_7	SDRAM Buffer HL Prop. Delay ³	Input edge greater than 1 V/nS	1	2.7	3.5	nS
t_{PLZ}, t_{PHZ}	SDRAM Buffer Enable Delay ³	Input edge greater than 1 V/nS	1	3	5	nS
t_{PZL}, t_{PZH}	SDRAM Buffer Disable Delay ³	Input edge greater than 1 V/nS	1	3	5	nS
t_r	Rise Time for SDATA (Refer Test Circuit for IIC) Refer figure no.3	$C_L = 10pF$	6			nS
		$C_L = 400pF$			250	
t_f	Fall Time for SDATA (Refer Test Circuit for IIC) Refer figure no.3	$C_L = 10pF$	20			nS
		$C_L = 400pF$			250	

Note: 1. All parameters specified with loaded outputs.

2. Duty cycle of input clock is 50%. Rising and falling edge rate is greater than 1V/nS

3. Parameter is guaranteed by design and characterization. Not 100% tested in production.

Test Circuit for SDRAM Enable and Disable Times

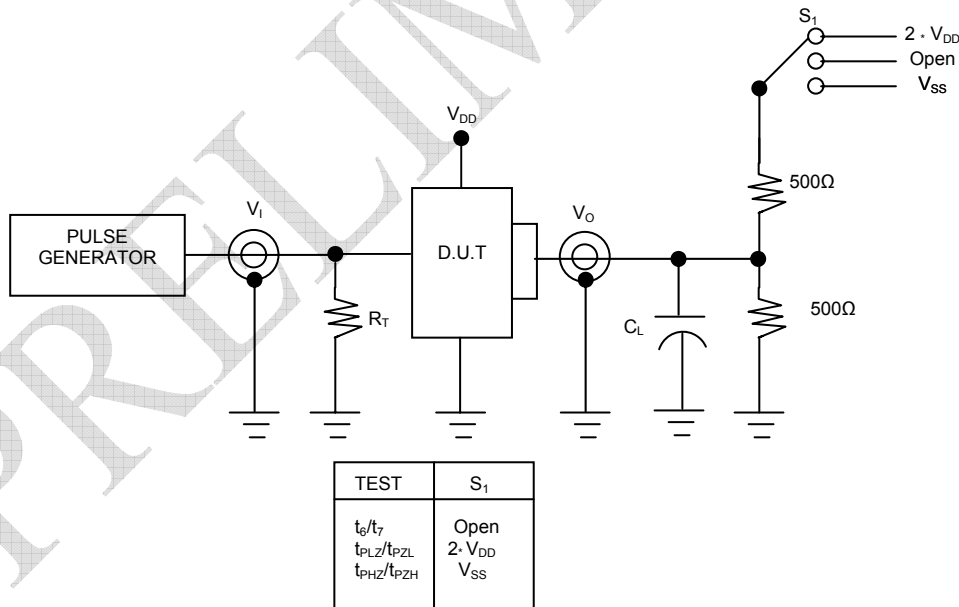


Figure 1. Load circuit for Switching times



rev 0.3

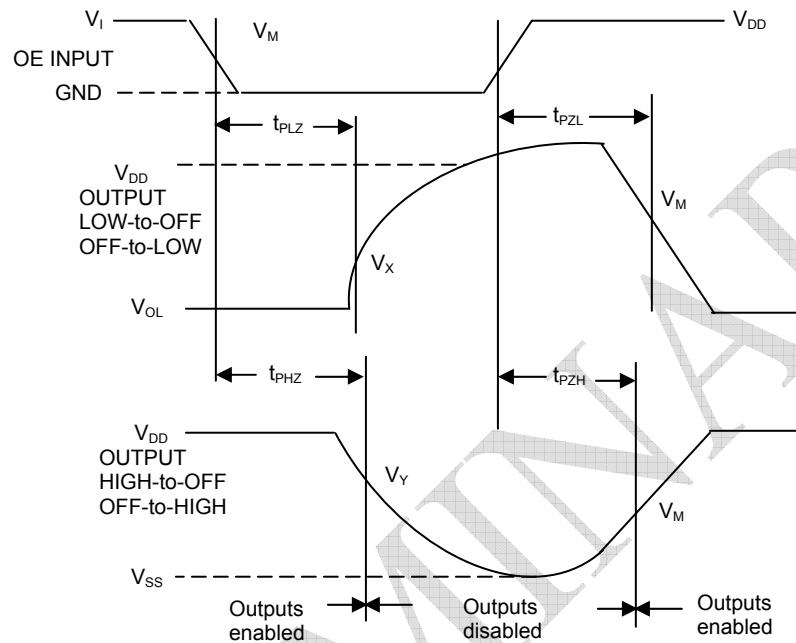
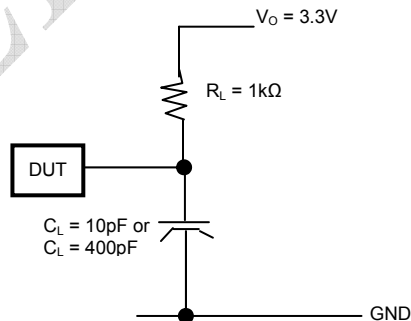
SDRAM Enable and Disable Times

$$V_M = 1.5V$$

$$V_X = V_{OL} + 0.3V$$

$$V_Y = V_{OH} - 0.3V$$

V_{OH} and V_{OL} are the typical Output Voltage drop that occur with the output load

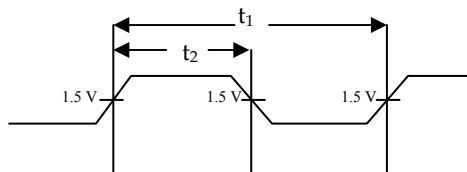
**Figure 2. 3-State Enable and Disable times****Test Circuit for IIC Rise and Fall Times****Figure 3. Test Circuit for IIC**



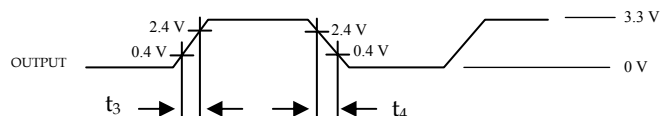
rev 0.3

Switching Waveforms

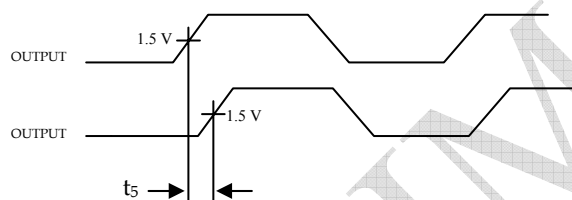
Duty Cycle Timing



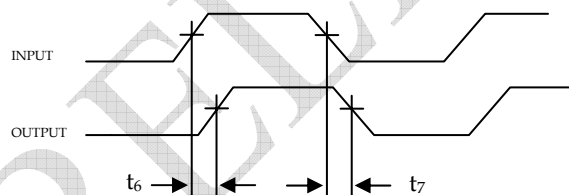
All Outputs Rise/Fall Time



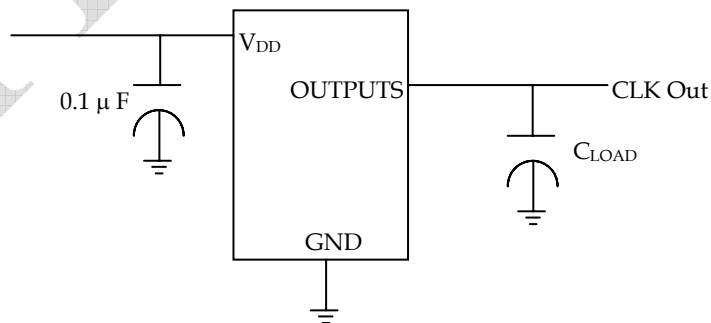
Output - Output Skew



SDRAM Buffer LH and HL Propagation Delay



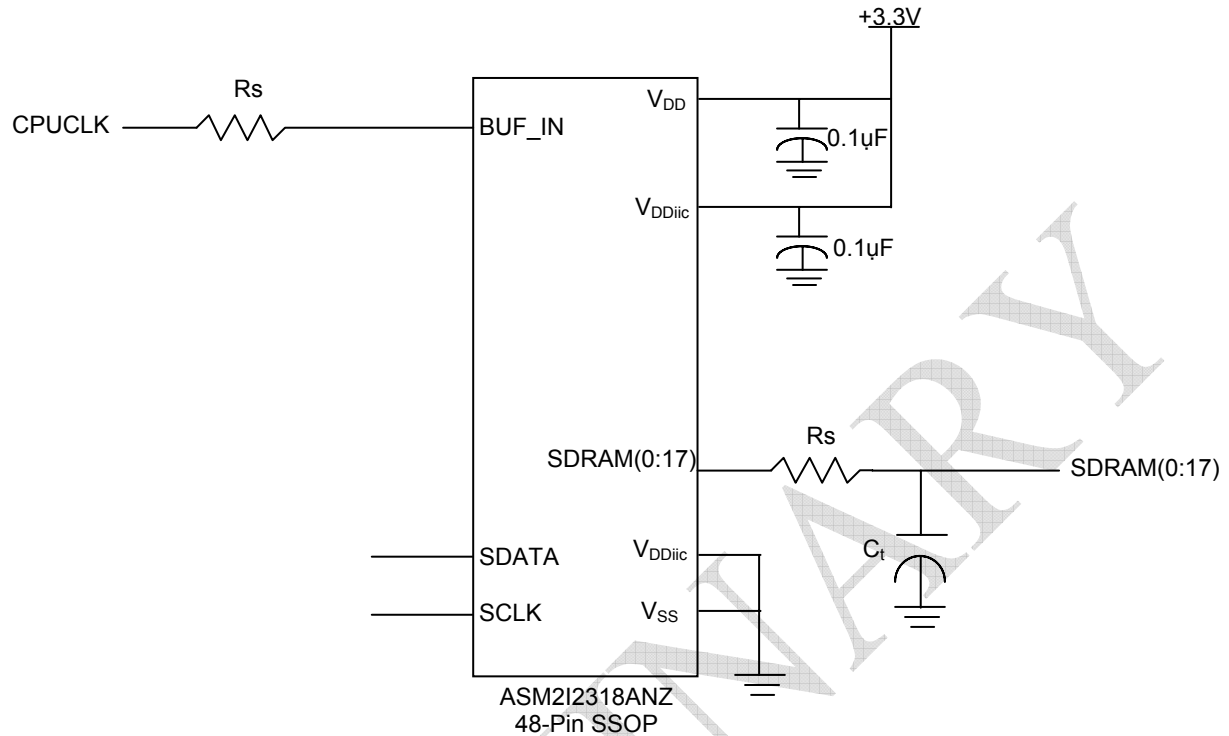
Test Circuit





rev 0.3

Application Circuit



Summary

- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1µF. In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where R_{trace} is the loaded characteristic impedance of the trace, R_{out} is the output impedance of the buffer (typically 25Ω), and R_{series} is the series terminating resistor.

$$R_{\text{series}} > R_{\text{trace}} - R_{\text{out}}$$
- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7pF to 22pF.
- A Ferrite Bead may be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50Ω impedance at the clock frequency, under loaded DC conditions.
- If a Ferrite Bead is used, a 10µF–22µF tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.



rev 0.3

IIC Serial Interface Information

The information in this section assumes familiarity with IIC programming.

How to program ASM2I2318ANZ through IIC:

- Master (host) sends a start bit.
- Master (host) sends the write address D3 (H).
- ASM2I2318ANZ device will acknowledge.
- Master (host) sends the Command Byte.
- ASM2I2318ANZ device will acknowledge the Command Byte.
- Master (host) sends a Byte count
- ASM2I2318ANZ device will acknowledge the Byte count.
- Master (host) sends the Byte 0
- ASM2I2318ANZ device will acknowledge Byte 0
- Master (host) sends the Byte 1
- ASM2I2318ANZ device will acknowledge Byte 1
- Master (host) sends the Byte 2
- ASM2I2318ANZ device will acknowledge Byte 2
- Master (host) sends a Stop bit.

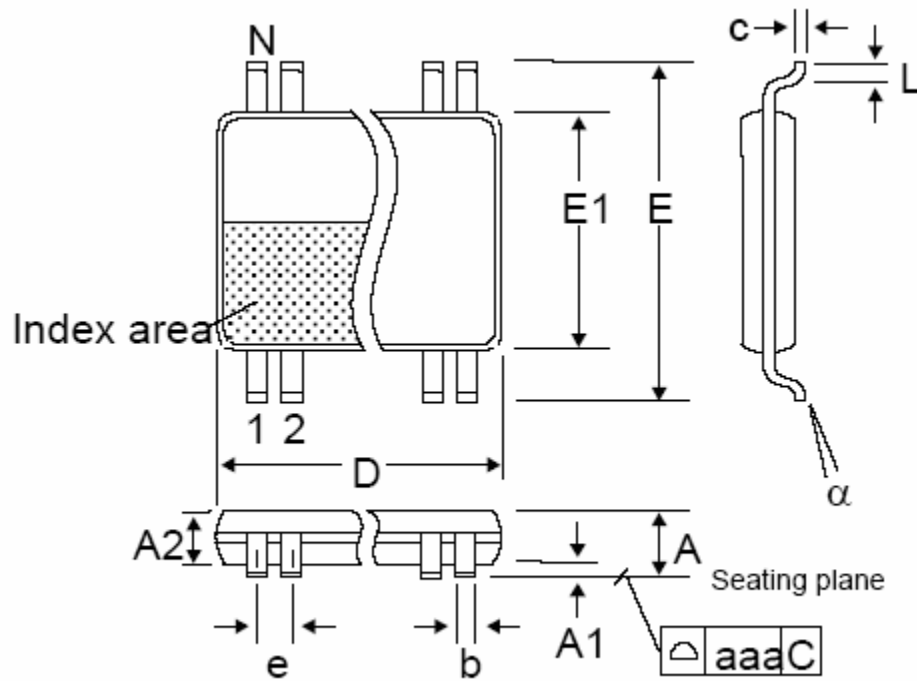
Controller (Host)	ASM2I2318ANZ (slave/receiver)
Start Bit	
Slave Address D3(H)	
	ACK
Command Byte	
	ACK
Byte count	
	ACK
Byte 0	
	ACK
Byte 1	
	ACK
Byte 2	
	ACK
Stop Bit	



rev 0.3

Package Information

48L SSOP Package (300 mil)



Symbol	Dimensions			
	Inches		Millimeters	
	Min	Max	Min	Max
A	0.095	0.110	2.413	2.794
A1	0.008	0.016	0.203	0.406
B	0.008	0.012	0.203	0.305
C	0.005	0.009	0.127	0.228
D	0.620	0.630	15.75	16.002
E	0.291	0.299	7.39	7.59
H	0.395	0.420	10.033	10.67
L	0.020	0.040	0.508	1.016
e	0.025 BSC		0.635 BSC	
α	0°	8°	0°	8°



rev 0.3

Ordering Information

Ordering Code	Marking	Package Type	Operating Range
ASM2I2318ANZ-48-AT	2I2318ANZ	48 Pin SSOP, Tube	Industrial
ASM2I2318ANZ-48-AR	2I2318ANZ	48 Pin SSOP, Tape and Reel	Industrial
ASM2I2318AGNZ-48-AT	2I2318AGNZ	48 Pin SSOP, Tube, Green	Industrial
ASM2I2318AGNZ-48-AR	2I2318AGNZ	48 Pin SSOP, Tape and Reel, Green	Industrial

Device Ordering Information

A S M 2 I 2 3 1 8 A N Z G - 4 8 - A R

R = Tape & reel, T = Tube or Tray

O = SOT
S = SOIC
T = TSSOP
A = SSOP
V = TVSOP
B = BGA
Q = QFN

U = MSOP
E = TQFP
L = LQFP
U = MSOP
P = PDIP
D = QSOP
X = SC-70

DEVICE PIN COUNT

F = LEAD FREE AND RoHS COMPLIANT PART
G = GREEN PACKAGE

PART NUMBER

X = Automotive (-40C to +125C) I = Industrial (-40C to +85C) P or n/c = Commercial (0C to +70C)

1 = Reserved 6 = Power Management
2 = Non PLL based 7 = Power Management
3 = EMI Reduction 8 = Power Management
4 = DDR support products 9 = Hi Performance
5 = STD Zero Delay Buffer 0 = Reserved

ALLIANCE SEMICONDUCTOR MIXED SIGNAL PRODUCT



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Part Number: ASM2I2318ANZ
Document Version: 0.3

Note: This product utilizes US Patent # 6,646,463 Impedance Emulator Patent issued to Alliance Semiconductor, dated 11-11-2003

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